

High Speed +5V Powered RS-232 Transmitters/Receivers

The HIN232A high-speed RS-232 transmitter/receiver interface circuit meets all EIA high-speed RS-232E and V.28 specifications, and is particularly suited for those applications where $\pm 12V$ is not available. They require a single +5V power supply and feature onboard charge pump voltage converters which generate +10V and -10V supplies from the 5V supply.

The drivers feature true TTL/CMOS input compatibility, slew rate-limited output, and 300Ω power-off source impedance. The receivers can handle up to $\pm 30V$ input, and have a $3k\Omega$ to $7k\Omega$ input impedance. The receivers also feature hysteresis to greatly improve noise rejection.

Ordering Information

PART NO.	PART MARKING	TEMP. RANGE (°C)	PACKAGE	PKG. DWG. #
HIN232ACB	232ACB	0 to 70	16 Ld SOIC	M16.3
HIN232ACB-T	232ACB	0 to 70	16 Ld SOIC Tape and Reel	M16.3
HIN232ACBZ (See Note)	232ACBZ	0 to 70	16 Ld SOIC (Pb-free)	M16.3
HIN232ACBZ-T (See Note)	232ACBZ	0 to 70	16 Ld SOIC Tape and Reel (Pb-free)	M16.3
HIN232ACBN	232ACBN	0 to 70	16 Ld SOIC (N)	M16.15
HIN232ACBN-T	232ACBN	0 to 70	16 Ld SOIC (N) Tape and Reel	M16.15
HIN232ACBNZ (See Note)	232ACBNZ	0 to 70	16 Ld SOIC (N) (Pb-free)	M16.15
HIN232ACBNZ-T (See Note)	232ACBNZ	0 to 70	16 Ld SOIC (N) Tape and Reel (Pb-free)	M16.15
HIN232ACP	HIN232ACP	0 to 70	16 Ld PDIP	E16.3
HIN232ACPZ (See Note)	232ACPZ	0 to 70	16 Ld PDIP* (Pb-free)	E16.3

*Pb-free PDIPs can be used for through hole wave solder processing only. They are not intended for use in Reflow solder processing applications.

NOTE: Intersil Pb-free plus anneal products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

Selection Table

PART NUMBER	POWER SUPPLY VOLTAGE	NUMBER OF RS-232 DRIVERS	NUMBER OF RS-232 RECEIVERS	NUMBER OF 0.1 μ F EXTERNAL CAPACITORS	LOW POWER SHUTDOWN/TTL THREE-STATE	NUMBER OF RECEIVERS ACTIVE IN SHUTDOWN
HIN232A	+5V	2	2	4 Capacitors	No/No	0

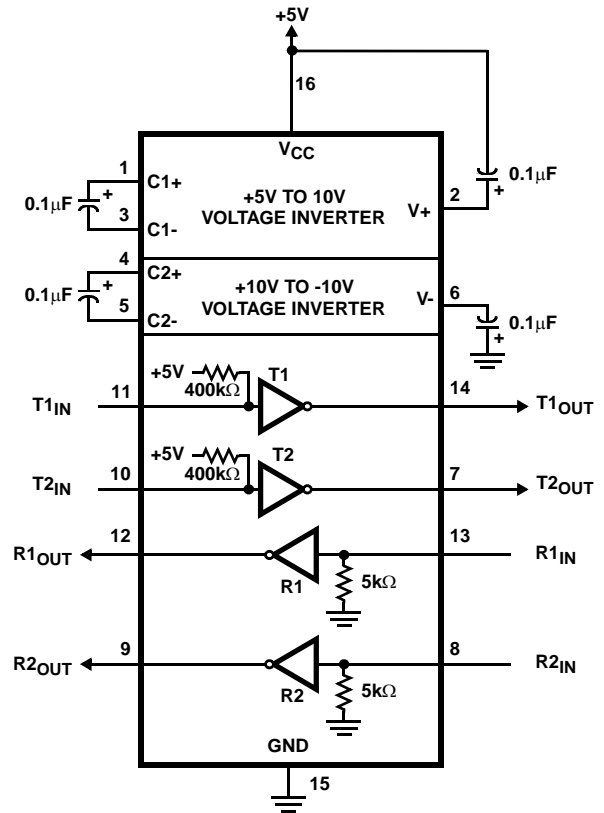
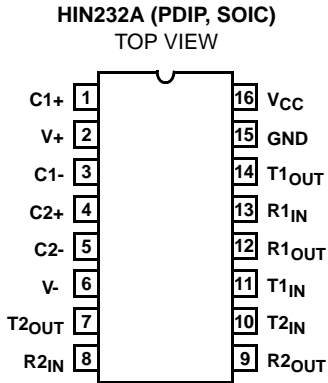
Features

- Meets All RS-232E and V.28 Specifications
- Requires Only 0.1 μ F or Greater External Capacitors
- High Data Rate. 230kbit/s
- Requires Only Single +5V Power Supply
- Onboard Voltage Doubler/Inverter
- Low Power Consumption (Typ) 5mA
- Multiple Drivers
 - $\pm 10V$ Output Swing for +5V Input
 - 300Ω Power-Off Source Impedance
 - Output Current Limiting
 - TTL/CMOS Compatible
- Multiple Receivers
 - $\pm 30V$ Input Voltage Range
 - $3k\Omega$ to $7k\Omega$ Input Impedance
 - 0.5V Hysteresis to Improve Noise Rejection
- Pb-Free Plus Anneal Available (RoHS Compliant)

Applications

- Any System Requiring High-Speed RS-232 Communication Ports
 - Computer - Portable, Mainframe, Laptop
 - Peripheral - Printers and Terminals
 - Instrumentation, UPS
 - Modems

Pinout



Pin Descriptions

PIN	FUNCTION
V _{CC}	Power Supply Input 5V ±10%.
V+	Internally generated positive supply (+10V nominal).
V-	Internally generated negative supply (-10V nominal).
GND	Ground Lead. Connect to 0V.
C1+	External capacitor (+ terminal) is connected to this lead.
C1-	External capacitor (- terminal) is connected to this lead.
C2+	External capacitor (+ terminal) is connected to this lead.
C2-	External capacitor (- terminal) is connected to this lead.
T _{IN}	Transmitter Inputs. These leads accept TTL/CMOS levels. An internal 400kΩ pull-up resistor to V _{CC} is connected to each lead.
T _{OUT}	Transmitter Outputs. These are RS-232 levels (nominally ±10V).
R _{IN}	Receiver Inputs. These inputs accept RS-232 input levels. An internal 5kΩ pull-down resistor to GND is connected to each input.
R _{OUT}	Receiver Outputs. These are TTL/CMOS levels.

impedance, $V_{CC} = 4.5V$, and maximum allowable operating temperature. The transmitters have an internally limited output slew rate which is less than $30V/\mu s$. The outputs are short circuit protected and can be shorted to ground indefinitely. The powered down output impedance is a minimum of 300Ω with $\pm 2V$ applied to the outputs and $V_{CC} = 0V$.

Receivers

The receiver inputs accept up to $\pm 30V$ while presenting the required $3k\Omega$ to $7k\Omega$ input impedance even if the power is off ($V_{CC} = 0V$). The receivers have a typical input threshold of $1.3V$ which is within the $\pm 3V$ limits, known as the transition region, of the RS-232 specifications. The receiver output is $0V$ to V_{CC} . The output will be low whenever the input is greater than $2.4V$ and high whenever the input is floating or driven between $+0.8V$ and $-30V$. The receivers feature $0.5V$ hysteresis (except during shutdown) to improve noise rejection.

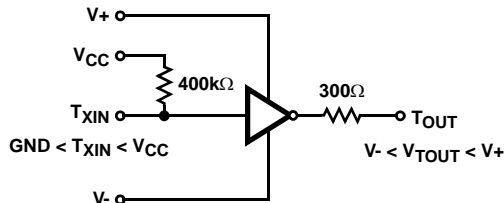


FIGURE 4. TRANSMITTER

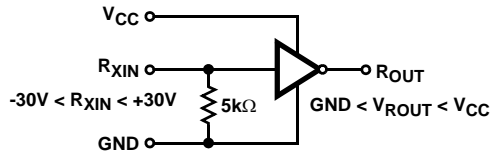
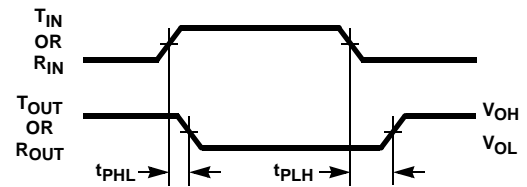


FIGURE 5. RECEIVER



$$\text{AVERAGE PROPAGATION DELAY} = \frac{t_{PHL} + t_{PLH}}{2}$$

FIGURE 6. PROPAGATION DELAY DEFINITION

Application Information

The HIN232A may be used for all RS-232 data terminal and communication links. It is particularly useful in applications where $\pm 12V$ power supplies are not available for conventional RS-232 interface circuits. The applications presented represent typical interface configurations.

A simple duplex RS-232 port with CTS/RTS handshaking is illustrated in Figure 7. Fixed output signals such as DTR (data terminal ready) and DSRS (data signaling rate select) is generated by driving them through a $5k\Omega$ resistor connected to $V+$.

In applications requiring four RS-232 inputs and outputs (Figure 8), note that each circuit requires two charge pump capacitors (C1 and C2) but can share common reservoir capacitors (C3 and C4). The benefit of sharing common reservoir capacitors is the elimination of two capacitors and the reduction of the charge pump source impedance which effectively increases the output swing of the transmitters.

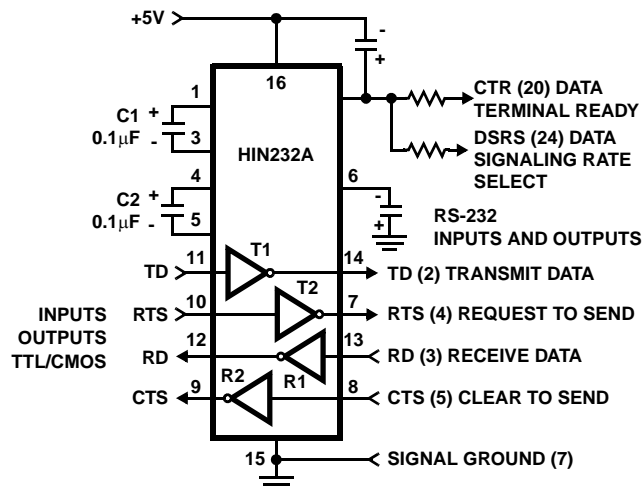


FIGURE 7. SIMPLE DUPLEX RS-232 PORT WITH CTS/RTS HANDSHAKING

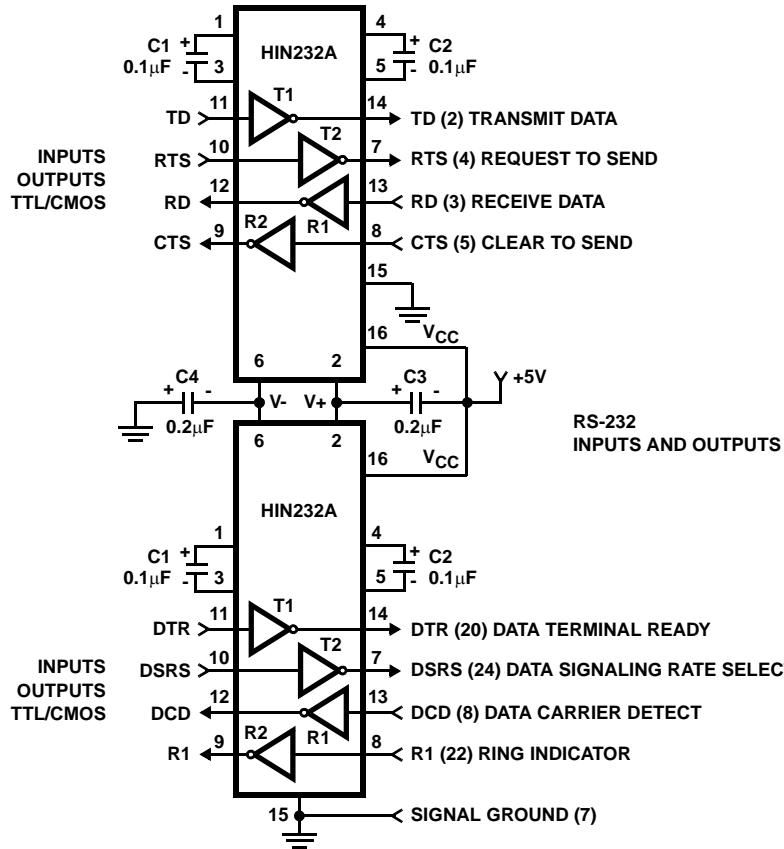


FIGURE 8. COMBINING TWO HIN232As FOR 4 PAIRS OF RS-232 INPUTS AND OUTPUTS

Typical Performance Curves

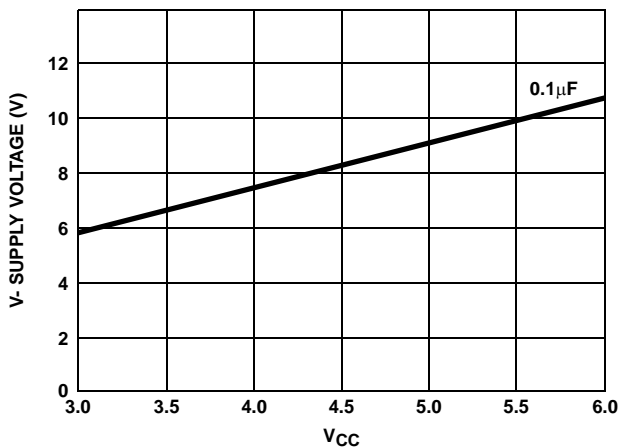


FIGURE 9. V- SUPPLY VOLTAGE vs V_{CC}

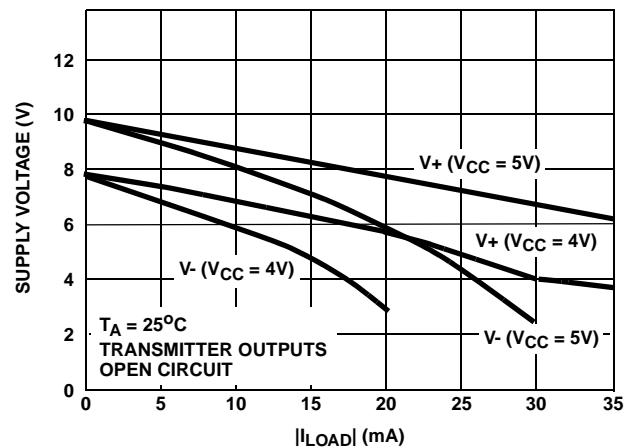


FIGURE 10. V₊, V₋ OUTPUT VOLTAGE vs LOAD

Die Characteristics

DIE DIMENSIONS

160 mils x 140 mils

METALLIZATION

Type: Al

Thickness: $10\text{k}\text{\AA} \pm 1\text{k}\text{\AA}$

SUBSTRATE POTENTIAL

V+

PASSIVATION

Type: Nitride over Silox

Nitride Thickness: $8\text{k}\text{\AA}$

Silox Thickness: $7\text{k}\text{\AA}$

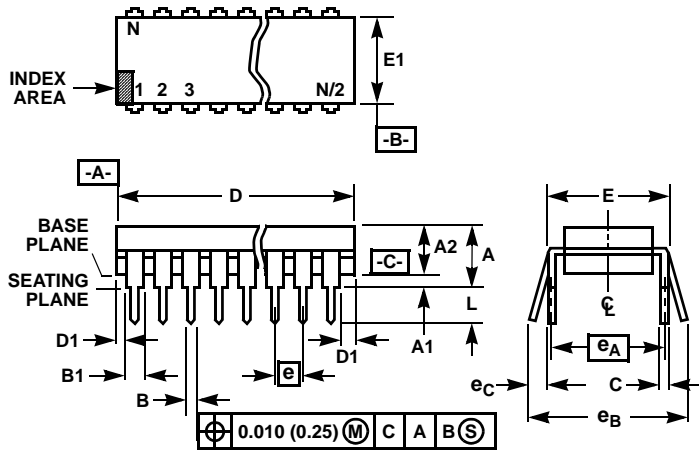
TRANSISTOR COUNT

238

PROCESS

CMOS Metal Gate

Dual-In-Line Plastic Packages (PDIP)



NOTES:

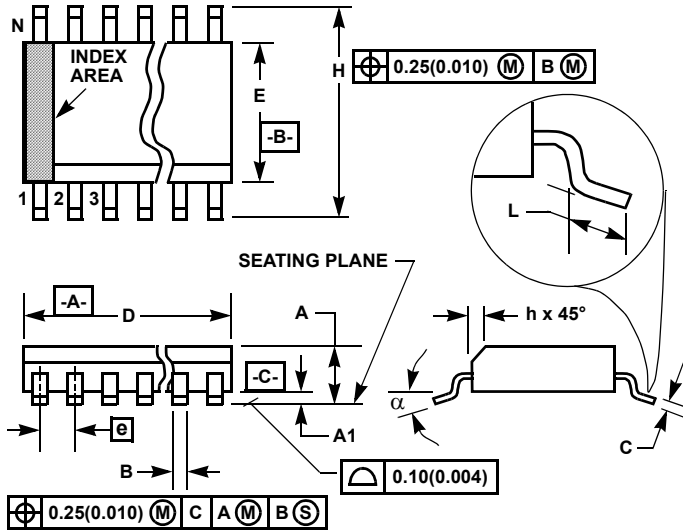
1. Controlling Dimensions: INCH. In case of conflict between English and Metric dimensions, the inch dimensions control.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication No. 95.
4. Dimensions A, A1 and L are measured with the package seated in JEDEC seating plane gauge GS-3.
5. D, D1, and E1 dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 inch (0.25mm).
6. E and e_A are measured with the leads constrained to be perpendicular to datum [-C-].
7. e_B and e_C are measured at the lead tips with the leads unconstrained. e_C must be zero or greater.
8. B1 maximum dimensions do not include dambar protrusions. Dambar protrusions shall not exceed 0.010 inch (0.25mm).
9. N is the maximum number of terminal positions.
10. Corner leads (1, N, N/2 and N/2 + 1) for E8.3, E16.3, E18.3, E28.3, E42.6 will have a B1 dimension of 0.030 - 0.045 inch (0.76 - 1.14mm).

E16.3 (JEDEC MS-001-BB ISSUE D)
16 LEAD DUAL-IN-LINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.210	-	5.33	4
A1	0.015	-	0.39	-	4
A2	0.115	0.195	2.93	4.95	-
B	0.014	0.022	0.356	0.558	-
B1	0.045	0.070	1.15	1.77	8, 10
C	0.008	0.014	0.204	0.355	-
D	0.735	0.775	18.66	19.68	5
D1	0.005	-	0.13	-	5
E	0.300	0.325	7.62	8.25	6
E1	0.240	0.280	6.10	7.11	5
e	0.100 BSC		2.54 BSC		-
e_A	0.300 BSC		7.62 BSC		6
e_B	-	0.430	-	10.92	7
L	0.115	0.150	2.93	3.81	4
N	16		16		9

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Small Outline Plastic Packages (SOIC)



**M16.3 (JEDEC MS-013-AA ISSUE C)
16 LEAD WIDE BODY SMALL OUTLINE PLASTIC PACKAGE**

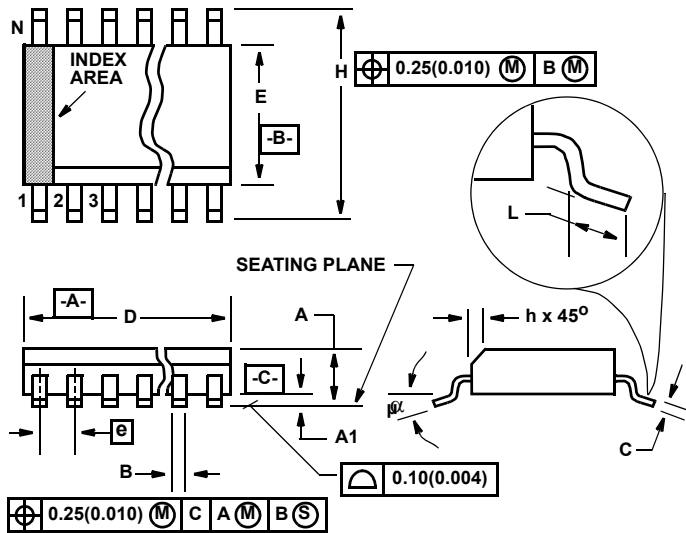
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.0926	0.1043	2.35	2.65	-
A1	0.0040	0.0118	0.10	0.30	-
B	0.013	0.0200	0.33	0.51	9
C	0.0091	0.0125	0.23	0.32	-
D	0.3977	0.4133	10.10	10.50	3
E	0.2914	0.2992	7.40	7.60	4
e	0.050 BSC		1.27 BSC		-
H	0.394	0.419	10.00	10.65	-
h	0.010	0.029	0.25	0.75	5
L	0.016	0.050	0.40	1.27	6
N	16		16		7
α	0°	8°	0°	8°	-

NOTES:

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch)
10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

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Small Outline Plastic Packages (SOIC)



**M16.15 (JEDEC MS-012-AC ISSUE C)
16 LEAD NARROW BODY SMALL OUTLINE PLASTIC PACKAGE**

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.053	0.069	1.35	1.75	-
A1	0.004	0.010	0.10	0.25	-
B	0.014	0.019	0.35	0.49	9
C	0.007	0.010	0.19	0.25	-
D	0.386	0.394	9.80	10.00	3
E	0.150	0.157	3.80	4.00	4
e	0.050 BSC		1.27 BSC		-
H	0.228	0.244	5.80	6.20	-
h	0.010	0.020	0.25	0.50	5
L	0.016	0.050	0.40	1.27	6
N	16		16		7
α	0°	8°	0°	8°	-

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NOTES:

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch)
10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

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